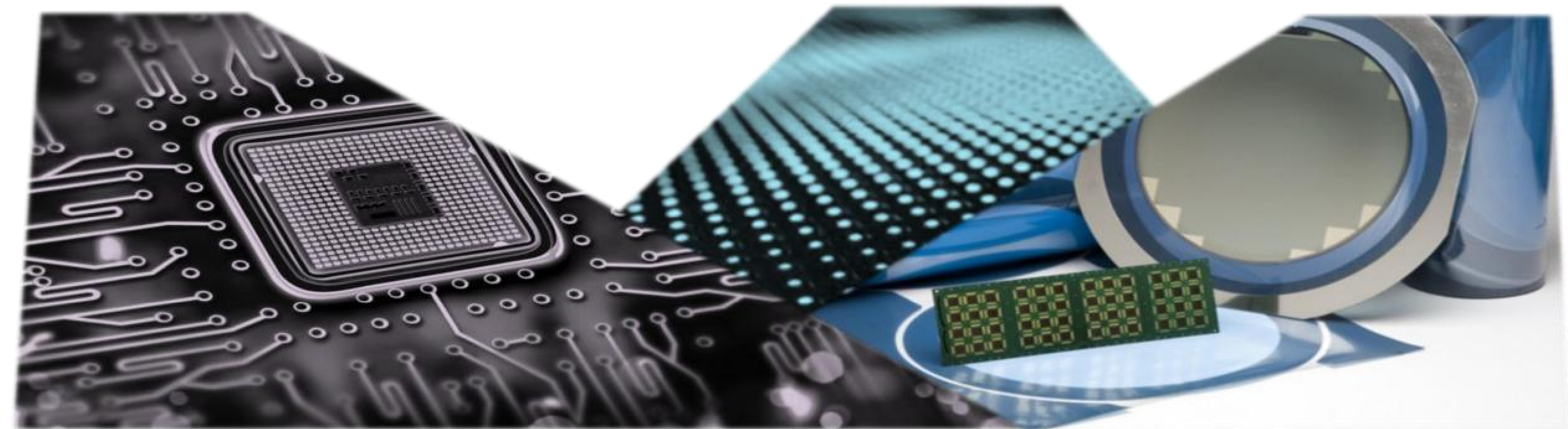
Yousan tape

YOUSAN

Products & Applications Overview

#UV dicing Tapes #Molding Tapes #Masking Tapes #Functional Tapes

2025



Manufacturing & Process Capabilities

Yousan tape

- **Design Capacity:** 16 million m²/year (including 7 million m² dedicated to semiconductor production)
- **Production Line Layout:** 5 total lines (2 dedicated to semiconductors)
- **Reserved Expansion:** Space for 5 additional lines
- **Manufacturing Team Leaders:** All with 10+ years of experience

@Huizhou Manufacturing Complex, Guangdong Province

Received Materials
IQC
Returns & Exchanges
NG
Warehousing
Material Issuing
dhesive Formulation
IPQC for Adhesive
Rework
Downgrade
Scrap
NG
Material Issuing
Coating Process
IPQC for Coating
Quarantine
Down grade
报废
NG
Semi-Finished Product Curing
Rewinding
Final Inspection
Packaging
Finished Goods-OQC
Put-Away
Order Picking
Demand Confirmation
Order Scheduling
Project Initiation Review
Project Team
Formula Pilot-Run 5-45days
Trial Production 5-15days
NG
Mass Production Sample Submission & Approval
NG
Mass Production Execution

Semiconductor Process & Product Application Roadmap

FEOL

Incoming Wafer

Film Lamination: Back-Grinding Tape

#In Development

Back-Grinding / Polishing

UV Curing & Tape Removal

Film Lamination: Wafer Dicing Tape

P6589

P4608

P6571

P4623

Laser / Stealth Dicing:

#Under Development

UV Release

Process Transfer / Film Packaging

#Pending Release

Die Pick & Pack

Wafer Dicing

Wafer Lamination

Film Lamination:
Package Dicing Tape

P4650

P46165

P4635

P4692

Laser / Stealth Dicing:

#Under Development

Carrier Tape Packaging

#Not Available

Lead Frame Pre-Lamination
Molding Tape :

P0119

P0113

Die Attach & Wire
Bonding

Resin Molding

Note: Laser Marking

#Under Development

Package Lamination

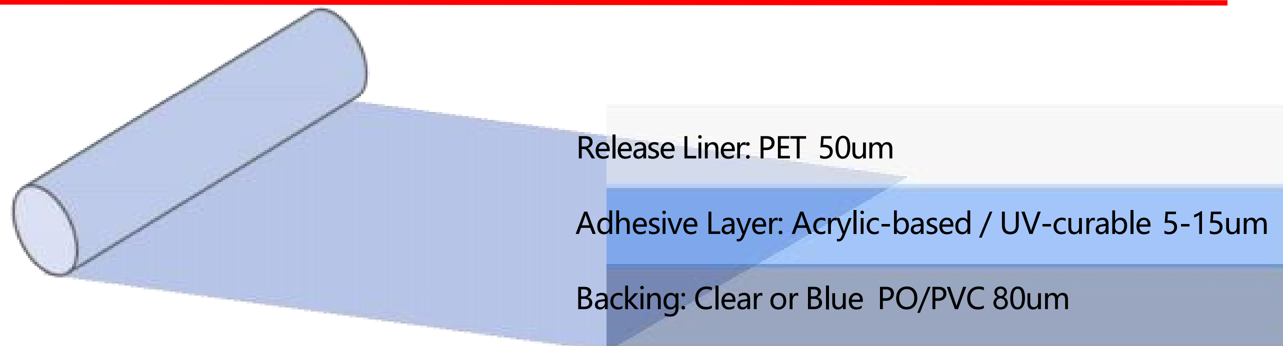
Unit Pick & Pack

Package Singulation

Wafer-Level Dicing Tape

Product Features:

- Compatible with a wide range of wafer substrates.
- Stable adhesion ensures minimal chipping and fly-off during dicing.
- Excellent isotropic uniformity for consistent film expansion.
- Clean residue-free release without contamination.
- Also suitable for back-grinding and temporary package protection in certain applications.



Product Code		P4670	P4608	P6589	P6597	P6512	P6571	P4623	P6518	P6509
Recommended Applications		Wafer Dicing and Protection								
Material / Appearance		PO	PO	Blue PVC	Clear PVC	Blue PVC	Clear PVC	PO	Blue PVC	Blue PVC
Backing Thickness um		80±3	80±3	80±3	80±3	80±3	80±3	80±3	80±3	80±3
Adhesive Thickness um		10±2	5±2	10±2	10±2	10±2	10±2	10±2	15±2	10±2
Total Thickness um		90±5	85±5	90±5	90±5	90±5	90±5	90±5	95±5	90±5
Release Liner Thickness um		50±2	50±2	50±2	50±2	50±2	50±2	50±2	50±2	50±2
Adhesion Strength - Mirror Wafer	Pre-UV N/25mm	≥8	≥4	≥1.5	≥1.5	≥6	≥7	1.5-2.5	2.0-4.0	≥0.8
	Post-UV N/25mm	≤0.15	≤0.15	≤0.15	≤0.1	≤0.25	≤0.15			
Release Condition	UV Dosage mJ/cm2	300-500	300-500	300-500	300-500	300-500	300-500	Non-UV Release Type		

Packaged Device Dicing Tape

Yousan tape

Product Features

- Compatible with a wide range of packaging substrates.
- Stable adhesion ensures minimal chipping and delamination during package singulation.
- Excellent isotropic uniformity for consistent film expansion.
- Clean residue-free release without contamination.
- Customizable to meet specific application requirements.

Release Liner: PET 50um

Adhesive Layer: Acrylic-based / UV-curable 10-35um

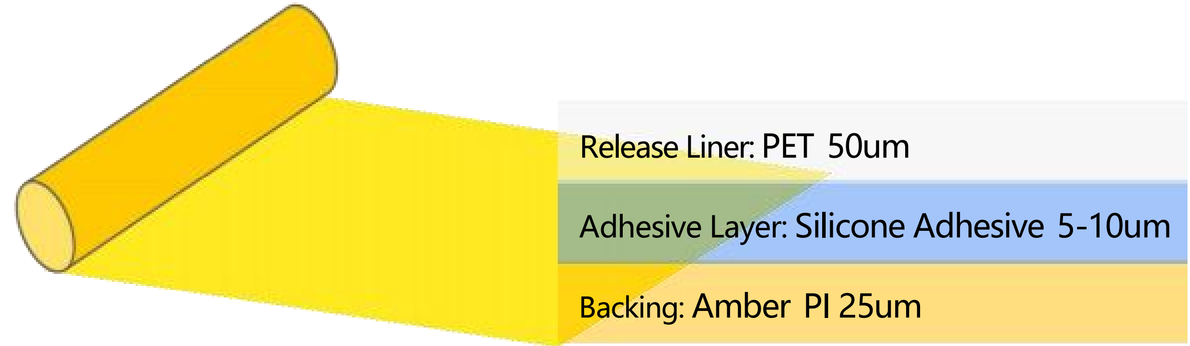
Backing: Clear PO 150um

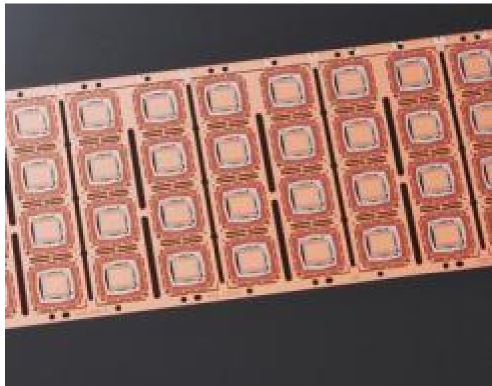
Product Code		P4650	P4633	P4631	P4637	P4668	P4659E	P4635	P4692	P4623	P46165
Recommended Applications		DFN, QFN, uQFN, uDFN					Static Dissipative DFN,QFN	mLED BGA, CSP	mLED EMC	mLED EMC	mLED Ceramic
Material / Appearance		PO	PO	PO	PO	PO	PO	PO	PO	PO	PO
Backing Thickness um		150±5	140±5	150±5	140±5	150±5	150±5	100±5	150±5	150±5	150±5
Adhesive Thickness um		25±2	15±2	10±2	10±2	10±2	30±2	20±2	10±2	10±2	15±2
Adhesive Thickness um		175±7	155±7	160±7	150±7	160±7	180±7	120±7	160±7	170±7	165±7
Release Liner Thickness um		50±2	50±2	50±2	50±2	50±2	50±2	50±2	50±2	50±2	50±2
Adhesion Strength - Standard Stainless Steel Panel	Pre-UV N/25mm	≥16	≥16	≥5	≥7	≥6	≥18	≥12	≥8	≥6	≥10
	Post-UV N/25mm	≤0.1	≤0.15	≤0.1	≤0.1	≤0.1	≤0.1	≤0.5	≤0.1	≤0.1	≤0.3
Release Condition	UV Dosage mJ/cm2	300-500	300-500	300-500	300-500	300-500	300-500	300-500	300-500	300-500	300-500

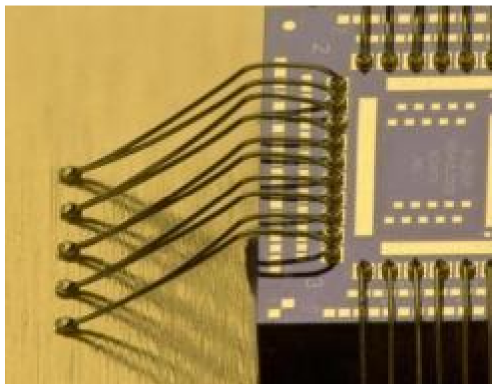
QFN/LCC Package Tapes

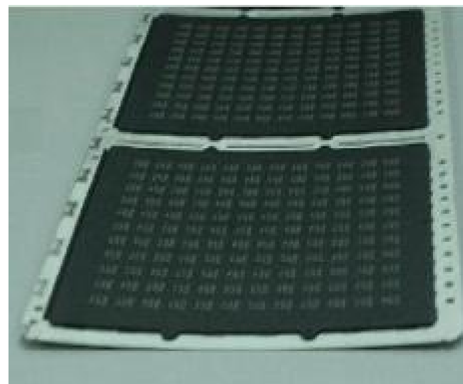
Product Features

- Moderate tack provides reliable adhesion to both copper and alloy leadframes.
- • Stable adhesion after high-temperature processes allows for clean and easy removal.
- • Excellent anti-bleed and dam-bar resistance properties.
- • Customizable to meet specific process requirements.









Product Code	P0119	P0113
Recommended Applications	QFN Assembly, Molding, Copper Leadframe 240° C x 30分 + 220° C x1H	
Material	PI	
Backing Thickness um	25±2	25±2
Adhesive Thickness um	5±2	10±2
Total Thickness um	30±4	35±4
Release Liner Thickness um	50±2	50±2
Adhesion Strength - Standard Steel Panel N/25mm	1-2	0.5-1

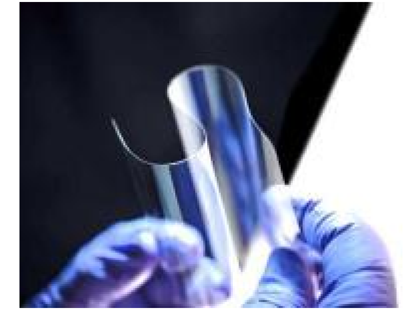
Process Tapes for Precision Industries

Product Features

- Excellent adhesion to a wide variety of substrates.
- Consistent tack ensures minimal debris generation during cutting/singulation.
- Robust performance under various process conditions with specialized chemical resistance.
- Clean, residue-free removal without surface contamination.
- Customizable to meet specific application and performance requirements.

Ceramic Components

Precision Glass Processing



Flexible Glass

Product Code		P49100	P4920D	P49221	P4613	P4612	P4651
Recommended Applications		Ceramic Dicing	Ceramic Dicing	Wafer	Filter Dicing	Filter Dicing	Glass Thinning
Material / Appearance		PET/Green	PET/Green	PET/Blue	PO	PO	PO
Backing Thickness um		50±2	100±3	50±2	80±3	80±3	150±3
Adhesive Thickness um		50±3	两面各50±3	50±3	20±2	10±2	35±2
Total Thickness um		100±5	200±9	100±5	100±5	90±5	185±5
Release Liner Thickness um		50±2	50±2	50±2	50±2	50±2	50±2
Adhesion Strength - Standard Steel Panel	Pre-UV N/25mm	≥8	≥0.4	≥8	≥10	≥6	≥20
	Post-UV N/25mm		Heat-Activated Removal		≤0.1	≤0.1	≤0.15
Release Condition	UV Dosage mJ/cm²				300-500	300-500	300-500
	Temperature & Time	100-110℃ 90s	130-150℃ 60s	120℃ 90s			

Yousan tape

Q&A

Innovate. Evolve. Collaborate. Succeed Together.

THANKS